

OKI Semiconductor

MSM64P164

4-Bit Microcontroller with Built-in RC Oscillation Type A/D Converter and LCD Driver

This version: Feb. 2000
Previous version: Sep. 1998

GENERAL DESCRIPTION

The MSM64P164 is a one-time-programmable ROM-version product, which has one-time PROM (OTP) as internal program memory. On the other hand, the MSM64164C is a mask ROM-version product, which has mask ROM as internal program memory.

Unlike the mask ROM-version MSM64164C, which has a P-well CMOS structure, the MSM64P164 has been fabricated with the N-well CMOS-structured EEPROM process technology. Therefore, the MSM64P164 differs from the MSM64164C in the polarity of the power supply for LCD bias generation and 5 V interface, and in the external circuit structure.

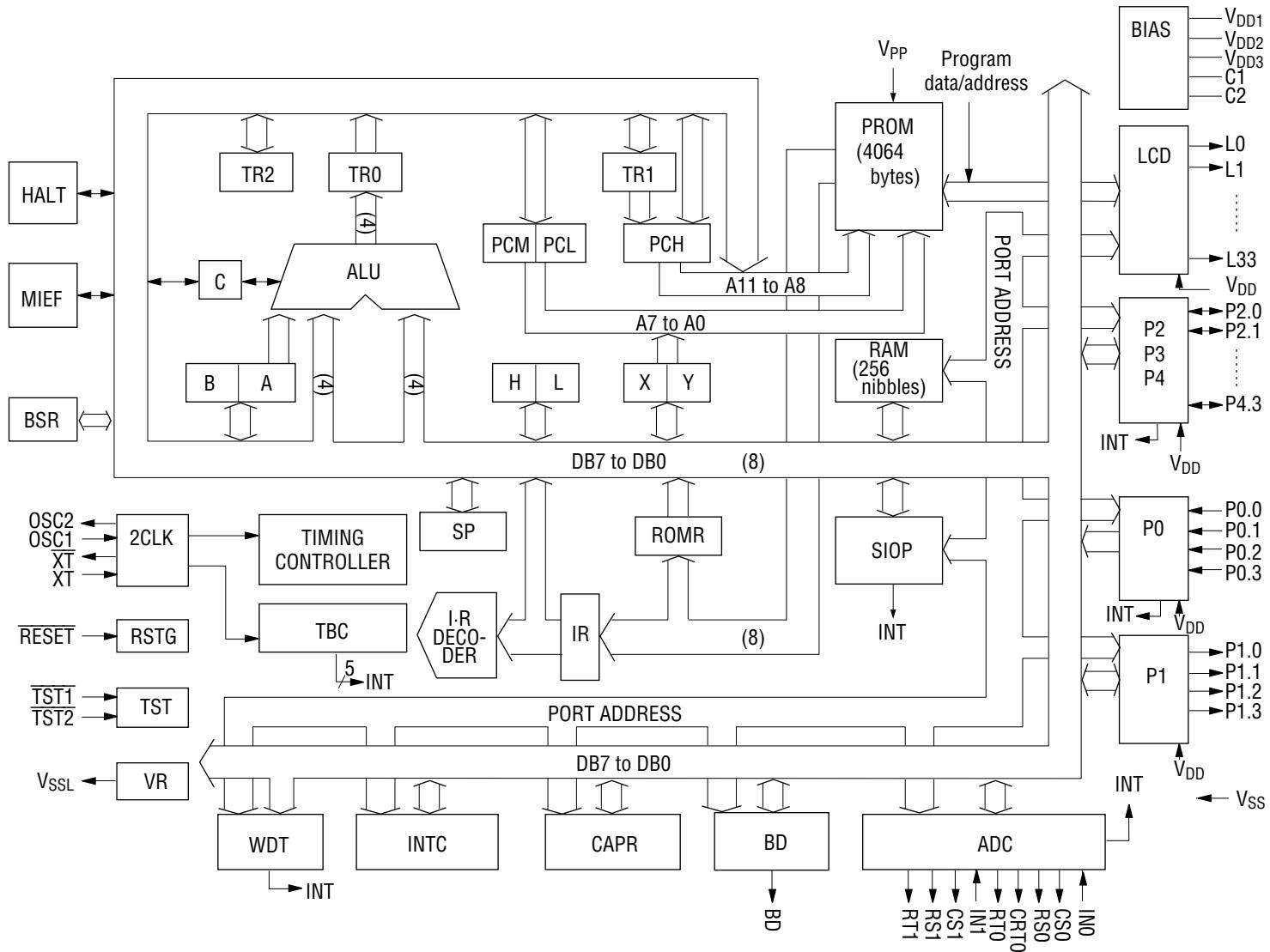
Unlike the mask ROM-version product, the MSM64P164 cannot be supplied in the form of a chip. The MSM64P164 is an OTP-version product used to evaluate an application program.

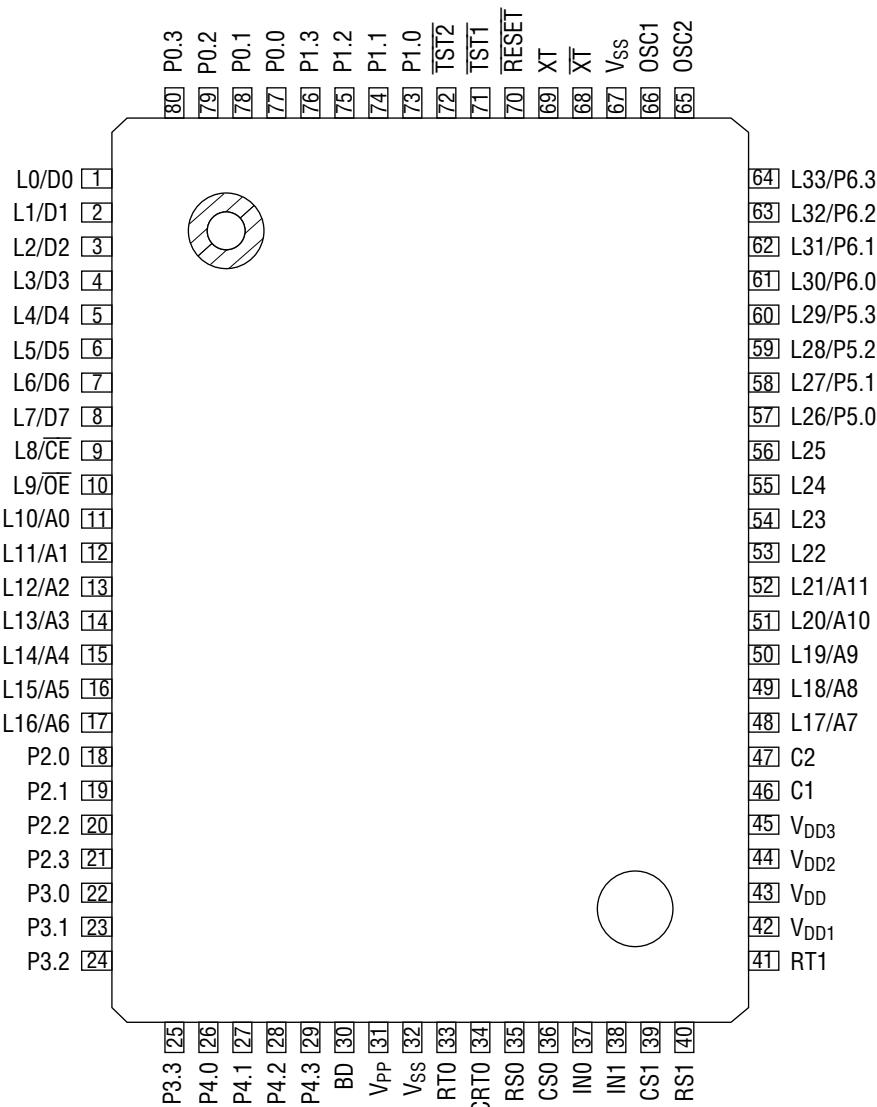
The MSM64P164 has two operation modes, microcontroller operation mode and PROM mode. The microcontroller operation mode is used to operate the MSM64P164 like a mask ROM-version product and the PROM mode is used to program or read the PROM.

FEATURES

- Operating range
 - Operating frequencies : 32.768 kHz, 400 kHz
 - Operating voltage : 1.5 V/3.0 V selectable by mask option
 - Operating temperature : Low supply current
 - Operating temperature : 0 to +65°C
- Memory space
 - Internal program memory : 4064 bytes
 - Internal data memory : 256 nibbles
- RC oscillation type A/D converter
 - Counter A : 2 channels
 - Counter B : Time dividing 2-channel method
 - Counter B : $1/(10^4 \times 8) \times 1$
 - Counter B : $1/2^{14} \times 1$
 - Serial port : Synchronous 8-bit transfer
 - Serial port : External clock/internal clock selectable
 - Serial port : MSB first/LSB first selectable
- LCD driver
 - (1) At 1/4 duty and 1/3 bias : 34 outputs; duty ratio switchable by software
 - (2) At 1/3 duty and 1/3 bias : 120 segments (max)
 - (3) At 1/2 duty and 1/2 bias : 93 segments (max)
 - (3) At 1/2 duty and 1/2 bias : 64 segments (max)
- Buzzer driver
 - Buzzer driver : 1 output (4 output modes selectable)
- Capture circuit
 - Capture circuit : 2 channels (256 Hz, 128 Hz, 64 Hz, 32 Hz)
- Watchdog timer
- I/O port
 - Input-output port : 3 ports \times 4 bits
 - Input port : 1 port \times 4 bits
 - Output port : 1 port \times 4 bits

- Interrupt sources
 - External interrupt : 2 sources
 - Internal interrupt : 8 sources
- Package:
80-pin plastic QFP (QFP80-P-1420-0.80-BK) : (Product name : MSM64P164-xxxxGS-BK)
xxxx indicates a code number.

BLOCK DIAGRAM

PIN CONFIGURATION (TOP VIEW)**80-Pin Plastic QFP**

Note: Because pin 32 and pin 67 are internally connected with each other, V_{SS} can be supplied from either pin 32 or pin 67.

PIN DESCRIPTIONS**Basic Functions**

Function	Pin	Symbol	Type	Description
Power Supply	32, 67	V _{SS}	—	0 V power supply
	42	V _{DD1}	—	Bias output for driving LCD (+1.5 V), or positive power supply at 1.5 V spec.
	44	V _{DD2}	—	Bias output for driving LCD (+3.0 V), or positive power supply at 3.0 V spec.
	45	V _{DD3}	—	Bias output for driving LCD (+4.5 V).
	43	V _{DD}	—	Positive power supply for I/O port interface
	31	V _{PP}	—	Positive power supply for writing to PROM (+12.5 V)
	46, 47	C ₁ , C ₂	—	Pins for connecting a capacitor for generating LCD driving bias.
Oscillation	69	XT	I	32.768 kHz crystal connection pins
	68	XT	O	
	66	OSC1	I	External 400 kHz oscillation resistor (R _{OS}) connection pins
	65	OSC2	O	
Ports	73 to 76	P1.0 to P1.3	O	Output port (P1.0 : high current output)
	77 to 80	P0.0 to P0.3	I	Input port
	18 to 29	P2.0 to P4.3	I/O	Input-output ports
	30	BD	O	Output pin for the buzzer driver
A/D Converter	33	RT0	O	Resistance temperature sensor connection pin
	34	CRT0	O	Resistance/capacitance temperature sensor connection pin
	35	RS0	O	Reference resistor connection pin
	36	CS0	O	Reference capacitor connection pin
	37	IN0	I	Input pin for RC oscillator circuit
	41	RT1	O	Resistance temperature sensor connection pin
	40	RS1	O	Reference resistor connection pin
	39	CS1	O	Reference capacitor connection pin
Reset	38	IN1	I	Input pin for RC oscillator circuit
	70	RESET	I	System reset input pin. Setting this pin to "L" level puts this device into a reset state. Then, setting this pin to "H" level starts executing an instruction from address 000H. This pin is internally pulled up to V _{DD} .
Test	71	TST1	I	Input pins for testing.
	72	TST2	I	
LCD Drivers	1 to 17, 48 to 56	L0 to L25	O	LCD driver pins
	57 to 64	L26/P5.0 to L33/P6.3	O	LCD driver pins, or output ports by mask option

Secondary Functions

Function	Pin	Symbol	Type	Description
External Interrupt	77	P0.0	I	Secondary functions of P0.0 to P0.3: Level-triggered external interrupt input pins. The change of input signal level causes an interrupt to occur.
	78	P0.1		
	79	P0.2		
	80	P0.3		
	18	P2.0		Secondary functions of P2.0 to P2.3, P3.0 to P3.3, and P4.0 to P4.3: Level-triggered external interrupt input pins. The change of input signal level causes an interrupt to occur.
	19	P2.1		
	20	P2.2		
	21	P2.3		
	22	P3.0		
	23	P3.1		
Capture Trigger	24	P3.2	I	
	25	P3.3		
Serial Port	26	P4.0	0	Secondary functions of P4.0: This pin is assigned the data output of a serial port (SOUT).
	27	P4.1	0	Secondary functions of P4.1: This pin is assigned the ready output of a serial port (SPR).
	28	P4.2	I/O	Secondary functions of P4.2: This pin is assigned the clock I/O of a serial port (SCLK).
	29	P4.3	0	Secondary functions of P4.3: This pin is a monitor output (MON) of an RC oscillation clock (OSCCLK) for an A/D converter and a 400 kHz RC oscillation clock for a system clock.

PROM-Related Pins

Function	Pin	Symbol	Type	Description
Program-ming	32, 67	V _{SS}	0	0 V power supply.
	42	V _{DD1} *	—	Positive power supply pin (+5 V supplied).
	44	V _{DD2} *	—	Positive power supply pin (+5 V supplied).
	31	V _{PP}	—	PROM write power supply (+12.5 V supplied).
	70	RESET	I	PROM write setting pins: PROM mode is set by a "L" level input.
	71	TST1		
	72	TST2		
	1	L0/D0	I/O	Pins for writing and reading program data.
	2	L1/D1		
	3	L2/D2		
	4	L3/D3		
	5	L4/D4		
	6	L5/D5		
	7	L6/D6		
	8	L7/D7		
	9	L8/CE	I/O	PROM chip enable pin.
	10	L9/OE	I/O	PROM output enable signal.
	11	L10/A0	I	Program address input pins.
	12	L11/A1		
	13	L12/A2		
	14	L13/A3		
	15	L14/A4		
	16	L15/A5		
	17	L16/A6		
	48	L17/A7		
	49	L18/A8		
	50	L19/A9		
	51	L20/A10		
	52	L21/A11		
	53	L22	I	Apply a "H" level to this pin.

* When in PROM mode, supply a 5 V power to both V_{DD1} and V_{DD2}.

ABSOLUTE MAXIMUM RATINGS (1.5 V Spec.)

(V _{SS} = 0 V)				
Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage 1	V _{DD1}	T _a = 25°C	-0.3 to +2.0	V
Power Supply Voltage 2	V _{DD2}	T _a = 25°C	-0.3 to +4.0	V
Power Supply Voltage 3	V _{DD3}	T _a = 25°C	-0.3 to +5.5	V
Power Supply Voltage 4	V _{DD}	T _a = 25°C	-0.3 to +5.5	V
Input Voltage 1	V _{IN1}	V _{DD1} input, T _a = 25°C	-0.3 to V _{DD1} + 0.3	V
Input Voltage 2	V _{IN2}	V _{DD} input, T _a = 25°C	-0.3 to V _{DD} + 0.3	V
Output Voltage 1	V _{OUT1}	V _{DD1} output, T _a = 25°C	-0.3 to V _{DD1} + 0.3	V
Output Voltage 2	V _{OUT2}	V _{DD2} output T _a = 25°C	-0.3 to V _{DD2} + 0.3	V
Output Voltage 3	V _{OUT3}	V _{DD3} output, T _a = 25°C	-0.3 to V _{DD3} + 0.3	V
Output Voltage 4	V _{OUT4}	V _{DD} output, T _a = 25°C	-0.3 to V _{DD} + 0.3	V
Storage Temperature	T _{STG}	—	-55 to +150	°C

RECOMMENDED OPERATING CONDITIONS (1.5 V Spec.)

(V _{SS} = 0 V)				
Parameter	Symbol	Condition	Range	Unit
Operating Temperature	T _{op}	—	0 to +65	°C
Operating Voltage	V _{DD1}	—	1.4 to 1.7	V
	V _{DD}	—	V _{DD1} to 5.25	V
External 400 kHz RC Oscillator Resistance	R _{OS}	—	250 to 500	kΩ
Crystal Oscillation Frequency	f _{XT}	—	30 to 35	kHz

ELECTRICAL CHARACTERISTICS (1.5 V Spec.)**DC Characteristics**(V_{SS} = 0 V, V_{DD1} = V_{DD} = 1.5 V, Ta = 0 to +65°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
V _{DD2} Voltage	V _{DD2}	C _a , C _b , C ₁₂ = 0.1 μF +100% -50%	2.8	3.0	3.2	V	1
V _{DD3} Voltage	V _{DD3}	C _a , C _b , C ₁₂ = 0.1 μF +100% -50%	4.3	4.5	4.7	V	
Crystal Oscillation Start Voltage	V _{STA}	Oscillation start time: within 5 seconds	1.47	—	—	V	
Crystal Oscillation Hold Voltage	V _{HOLD}	—	1.40	—	—	V	
Crystal Oscillation Stop Detection Time	T _{STOP}	—	0.1	—	1000	ms	
Internal Crystal Oscillator Capacitance	C _G	—	10	15	20	pF	
External Crystal Oscillator Capacitance	C _{GEX}	When external C _G used	10	—	30	pF	
Internal Crystal Oscillator Capacitance	C _D	—	10	15	20	pF	
Internal 400k RC Oscillator Capacitance	C _{OS}	—	8	12	16	pF	
400k RC Oscillation Frequency	f _{OSC}	External resistor R _{OS} = 300 kΩ V _{DD1} = 1.40 to 1.7 V	80	220	350	kHz	
POR Generation Voltage	V _{POR1}	When V _{DD1} is between V _{POR1} and 1.5 V	0	—	0.4	V	
POR Non-generation Voltage	V _{POR2}	No POR when V _{DD1} is between V _{POR2} and 1.5 V	1.4	—	1.5	V	

Notes: 1. "POR" denotes Power On Reset.

2. "T_{STOP}" indicates that if the crystal oscillator stops over the value of T_{STOP}, the system reset occurs.

DC Characteristics (continued)(V_{SS} = 0 V, V_{DD1} = V_{DD} = 1.5 V, Ta = 0 to +65°C unless otherwise specified)

Parameter	Symbol	Condition		Min.	Typ.	Max.	Unit	Measuring Circuit
Supply Current 1	I _{DD1}	CPU in halt state (400k RC oscillation halt)		—	2.0	5.0	μA	1
Supply Current 2	I _{DD2}	CPU in operating state (400k RC oscillation halt)		—	50	80	μA	
Supply Current 3	I _{DD3}	CPU in operating state (400k RC oscillation in operation) R _{OS} = 300 kΩ		—	90	180	μA	
Supply Current 4	I _{DD4}	Serial transfer, f _{SCK} = 300 kHz, CPU in operating state (400k RC oscillation halt)		—	60	100	μA	
Supply Current 5	I _{DD5}	CPU in halt state (400k RC oscillation halt), RC oscillator for A/D converter is in operating state	RT0 = 10 kΩ	—	150	230	μA	
			RT0 = 2 kΩ	—	600	900	μA	

DC Characteristics (continued)

($V_{SS} = 0 \text{ V}$, $V_{DD1} = V_{DD} = 1.5 \text{ V}$, $V_{DD2} = 3.0 \text{ V}$, $V_{DD3} = 4.5 \text{ V}$,
 $T_a = 0 \text{ to } +65^\circ\text{C}$ unless otherwise specified)

Parameter (Pin Name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
Output Current 1 (P1.0)	I_{OH1}	$V_{OH1} = V_{DD} - 0.5 \text{ V}$	-2.1	-0.7	-0.2	mA	2
	I_{OL1}	$V_{OL1} = 0.5 \text{ V}$	1.0	3.0	9.0	mA	
	I_{OL1S}	$V_{DD} = 5 \text{ V}$, $V_{OL1} = 0.5 \text{ V}$	4.0	12	36	mA	
Output Current 2 (P1.1 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	I_{OH2}	$V_{OH2} = V_{DD} - 0.5 \text{ V}$	-2.1	-0.7	-0.2	mA	2
	I_{OL2}	$V_{OL2} = 0.5 \text{ V}$	0.2	0.7	2.1	mA	
	I_{OL2S}	$V_{DD} = 5 \text{ V}$, $V_{OL2} = 0.5 \text{ V}$	1.0	3.0	9.0	mA	
Output Current 3 (BD)	I_{OH3}	$V_{OH3} = V_{DD1} - 0.7 \text{ V}$	-1.8	-0.6	-0.2	mA	2
	I_{OL3}	$V_{OL3} = 0.7 \text{ V}$	0.2	0.6	1.8	mA	
Output Current 4 (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OH4}	$V_{OH4} = V_{DD1} - 0.1 \text{ V}$	-1.1	-0.6	-0.3	mA	2
	I_{OL4}	$V_{OL4} = 0.1 \text{ V}$	0.3	0.6	1.1	mA	
Output Current 5 (When L26 to L33 are configured as output ports)	I_{OH5}	$V_{OH5} = V_{DD} - 0.5 \text{ V}$	-1.5	-0.5	-0.1	mA	2
	I_{OL5}	$V_{OL5} = 0.5 \text{ V}$	0.1	0.5	1.5	mA	
	I_{OL5S}	$V_{DD} = 5 \text{ V}$, $V_{OL5S} = 0.5 \text{ V}$	0.2	0.7	2.0	mA	
Output Current 6 (OSC2)	I_{OH6}	$V_{OH6} = V_{DD1} - 0.5 \text{ V}$	-2.1	-0.7	-0.2	mA	2
	I_{OL6}	$V_{OL6} = 0.5 \text{ V}$	0.2	0.7	2.1	mA	
Output Current 7 (L0 to L33)	I_{OH7}	$V_{OH7} = V_{DD3} - 0.2 \text{ V}$ (V_{DD3} level)	—	—	-4.0	μA	2
	I_{OMH7}	$V_{OMH7} = V_{DD2} + 0.2 \text{ V}$ (V_{DD2} level)	4.0	—	—	μA	
	I_{OMH7S}	$V_{OMH7S} = V_{DD2} - 0.2 \text{ V}$ (V_{DD2} level)	—	—	-4.0	μA	
	I_{OML7}	$V_{OML7} = V_{DD1} + 0.2 \text{ V}$ (V_{DD1} level)	4.0	—	—	μA	
	I_{OML7S}	$V_{OML7S} = V_{DD1} - 0.2 \text{ V}$ (V_{DD1} level)	—	—	-4.0	μA	
	I_{OL7}	$V_{OL7} = V_{SS} + 0.2 \text{ V}$ (V_{SS} level)	4.0	—	—	μA	
Output Leakage Current (P1.0 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3) (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OIH}	$V_{OH} = V_{DD1}$	—	—	0.3	μA	2
	I_{OOL}	$V_{OL} = V_{SS}$	-0.3	—	—	μA	

DC Characteristics (continued)

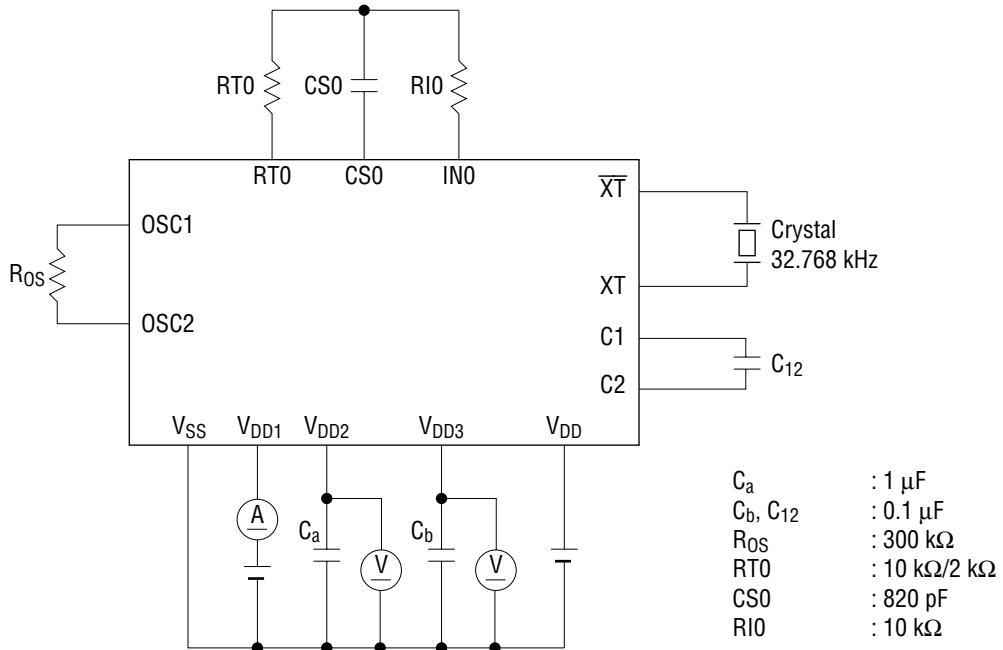
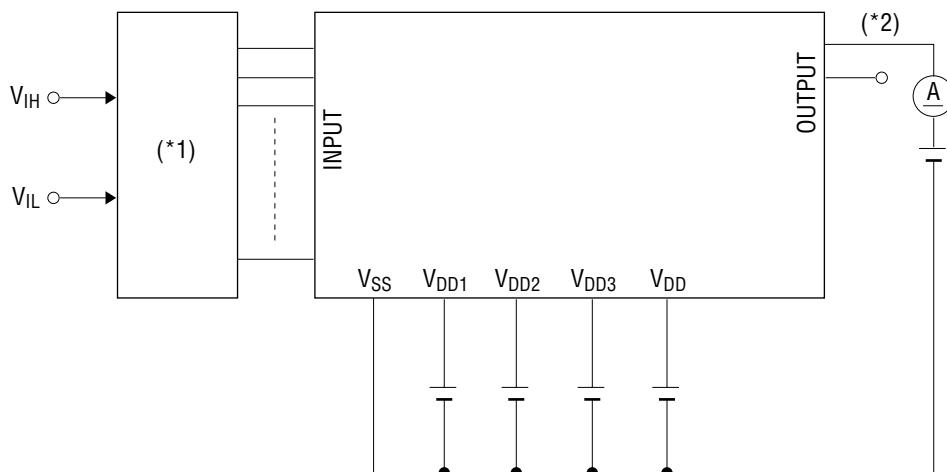
($V_{SS} = 0 \text{ V}$, $V_{DD1} = V_{DD} = 1.5 \text{ V}$, $V_{DD2} = 3.0 \text{ V}$, $V_{DD3} = 4.5 \text{ V}$,
 $T_a = 0 \text{ to } +65^\circ\text{C}$ unless otherwise specified)

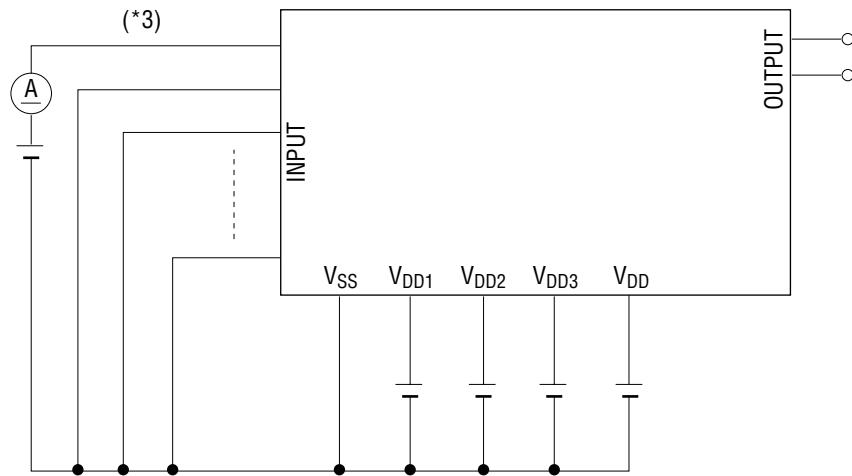
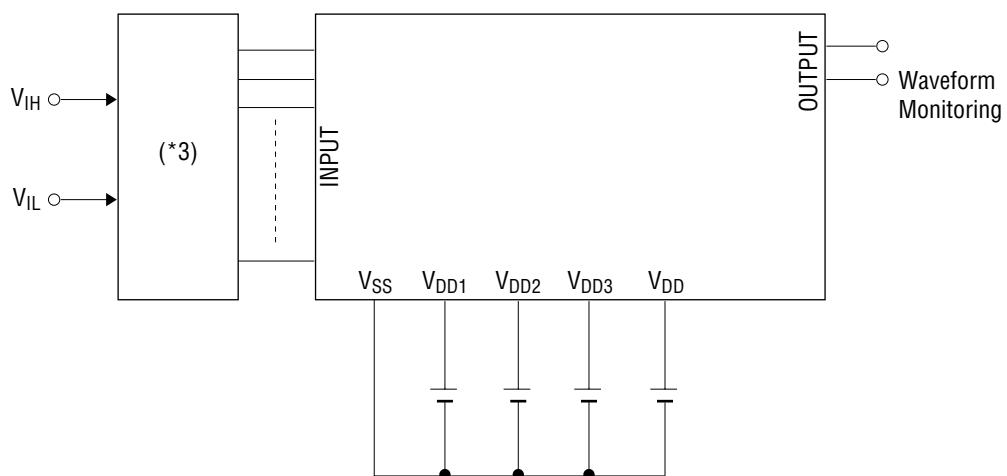
Parameter (Pin Name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
Input Current 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	I_{IH1}	$V_{IH1} = V_{DD}$ (when pulled down)	5.0	18	60	μA	3
	I_{IL1}	$V_{IL1} = V_{SS}$ (when pulled up)	-60	-18	-5.0	μA	
	I_{IH1S}	$V_{IH1} = V_{DD} = 5 \text{ V}$ (when pulled down)	70	250	660	μA	
	I_{IL1S}	$V_{IL1} = V_{SS}$, $V_{DD} = 5 \text{ V}$ (when pulled up)	-660	-250	-70	μA	
	I_{IH1Z}	$V_{IH1} = V_{DD}$ (in a high impedance state)	0	—	1.0	μA	
	I_{IL1Z}	$V_{IL1} = V_{SS}$ (in a high impedance state)	-1.0	—	0	μA	
Input Current 2 (IN0, IN1)	I_{IH2}	$V_{IH2} = V_{DD1}$ (when pulled down)	5.0	18	60	μA	3
	I_{IH2Z}	$V_{IH2} = V_{DD1}$ (in a high impedance state)	0	—	1.0	μA	
	I_{IL2Z}	$V_{IL2} = V_{SS}$ (in a high impedance state)	-1.0	—	0	μA	
Input Current 3 (OSC1)	I_{IL3}	$V_{IL3} = V_{SS}$ (when pulled up)	-60	-22	-6.0	μA	4
	I_{IH3Z}	$V_{IH3} = V_{DD1}$ (in a high impedance state)	0	—	1.0	μA	
	I_{IL3Z}	$V_{IL3} = V_{SS}$ (in a high impedance state)	-1.0	—	0	μA	
Input Current 4 (RESET, TST1, TST2)	I_{IH4}	$V_{IH4} = V_{DD1}$	0	—	1.0	μA	4
	I_{IL4}	$V_{IL4} = V_{SS}$	-1.0	-0.3	-0.1	mA	
Input Voltage 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	V_{IH1}	—	1.2	—	1.5	V	4
	V_{IL1}	—	0	—	0.3	V	
	V_{IH1S}	$V_{DD} = 5 \text{ V}$	4.0	—	5.0	V	
	V_{IL1S}	$V_{DD} = 5 \text{ V}$	0	—	1.0	V	
Input Voltage 2 (IN0, IN1, OSC1)	V_{IH2}	—	1.2	—	1.5	V	4
	V_{IL2}	—	0	—	0.3	V	
Input Voltage 3 (RESET, TST1, TST2)	V_{IH3}	—	1.2	—	1.5	V	4
	V_{IL3}	—	0	—	0.3	V	

DC Characteristics (continued)

($V_{SS} = 0$ V, $V_{DD1} = V_{DD} = 1.5$ V, $V_{DD2} = 3.0$ V, $V_{DD3} = 4.5$ V,
 $T_a = 0$ to $+65^\circ\text{C}$ unless otherwise specified)

Parameter (Pin Name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
Hysteresis Width (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	ΔV_{T1}	—	0.05	0.1	0.3	V	4
	ΔV_{T1S}	$V_{DD} = 5$ V	0.25	1.0	1.5	V	
Hysteresis Width (RESET, TST1, TST2)	ΔV_{T2}	—	0.05	0.1	0.3	V	
Input Pin Capacitance (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	C_{IN}	—	—	—	5.0	pF	1

Measuring circuit 1**Measuring circuit 2**

Measuring circuit 3**Measuring circuit 4**

*1 Input logic circuit to determine the specified measuring conditions.

*2 Measured at the specified output pins.

*3 Measured at the specified input pins.

A/D Converter Characteristics

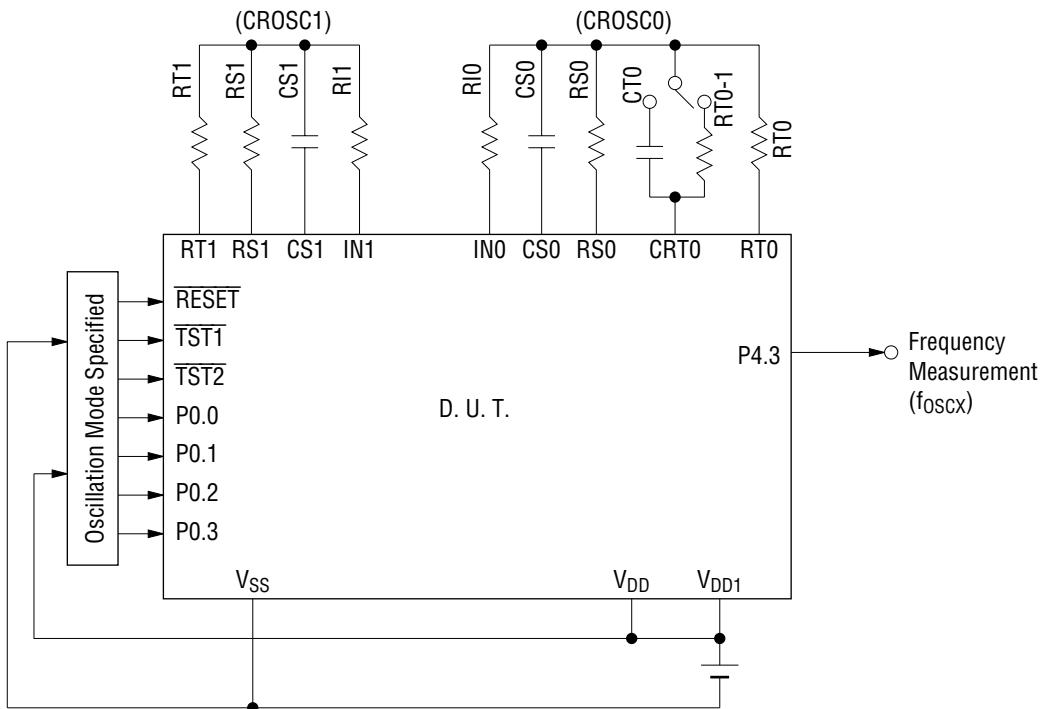
(V_{SS} = 0 V, V_{DD} = 1.5 V, Ta = 0 to +65°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measur-ing Circuit
Resistor for Oscillation	RS0, RS1, RT0, RT0-1, RT1	CS0, CT0, CS1 ≥ 740 pF	2.0	—	—	kΩ	5
Input Current Limiting Resistor	RI0, RI1	—	1.0	10	—	kΩ	
Oscillation Frequency	f _{osc1}	Resistor for oscillation = 2 kΩ	165	221	256	kHz	
	f _{osc2}	Resistor for oscillation = 10 kΩ	41.8	52.2	60.6	kHz	
	f _{osc3}	Resistor for oscillation = 200 kΩ	2.55	3.04	3.53	kHz	
RS•RT Oscillation Frequency Ratio (*)	Kf1	RT0, RT0-1, RT1 = 2 kΩ	3.89	4.18	4.35	—	5
	Kf2	RT0, RT0-1, RT1 = 10 kΩ	0.990	1.0	1.010	—	
	Kf3	RT0, RT0-1, RT1 = 200 kΩ	0.0561	0.0584	0.0637	—	

- * Kfx is the ratio of the oscillation frequency by a sensor resistor to the oscillation frequency by a reference resistor in the same condition.

$$K_{fx} = \frac{f_{oscx}(\text{RT0-CS0 Oscillation})}{f_{oscx}(\text{RS0-CS0 Oscillation})}, \frac{f_{oscx}(\text{RT0-1-CS0 Oscillation})}{f_{oscx}(\text{RS0-CS0 Oscillation})}, \frac{f_{oscx}(\text{RT1-CS1 Oscillation})}{f_{oscx}(\text{RS1-CS1 Oscillation})}$$

$$(x = 1, 2, 3)$$

Measuring circuit 5

RT0, RT0-1, RT1 = 2 kΩ/10 kΩ/200 kΩ

RS0, RS1 = 10 kΩ

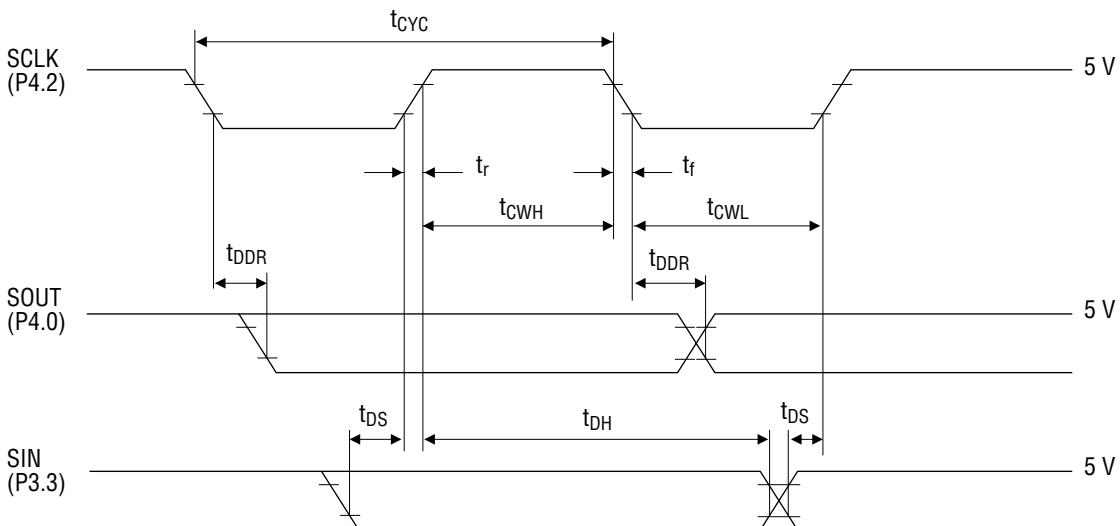
RI0, RI1 = 10 kΩ

CS0, CT0, CS1 = 820 pF

AC Characteristics (Serial Interface)

(V_{SS} = 0 V, V_{DD1} = 1.5 V, V_{DD} = 5 V, Ta = 0 to +65°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
SCLK Input Fall Time	t _f	—	—	15	50	ns
SCLK Input Rise Time	t _r	—	—	15	50	ns
SCLK Input "L" Level Pulse Width	t _{CWL}	—	0.8	—	—	μs
SCLK Input "H" Level Pulse Width	t _{CWH}	—	0.8	—	—	μs
SCLK Input Cycle Time	t _{CYC}	—	2.0	—	—	μs
SCLK Output Cycle Time	t _{CYC1(0)}	CPU is operating at 32.768 kHz.	—	30.5	—	μs
SCLK Output Cycle Time	t _{CYC2(0)}	CPU is operating at 400 kHz.	—	2.5	—	μs
SOUT Output Delay Time	t _{DDR}	C _I = 10 pF	—	—	0.4	μs
SIN Input Setup Time	t _{DS}	—	0.5	—	—	μs
SIN Input Hold Time	t _{DH}	—	0.8	—	—	μs



("H" level = 4 V, "L" level = 1 V)

ABSOLUTE MAXIMUM RATINGS (3.0 V Spec.)(V_{SS} = 0 V)

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage 1	V _{DD1}	T _a = 25°C	-0.3 to +2.0	V
Power Supply Voltage 2	V _{DD2}	T _a = 25°C	-0.3 to +4.0	V
Power Supply Voltage 3	V _{DD3}	T _a = 25°C	-0.3 to +5.5	V
Power Supply Voltage 4	V _{DD}	T _a = 25°C	-0.3 to +5.5	V
Input Voltage 1	V _{IN1}	V _{DD2} input, T _a = 25°C	-0.3 to V _{DD2} + 0.3	V
Input Voltage 2	V _{IN2}	V _{DD} input, T _a = 25°C	-0.3 to V _{DD} + 0.3	V
Output Voltage 1	V _{OUT1}	V _{DD2} output, T _a = 25°C	-0.3 to V _{DD2} + 0.3	V
Output Voltage 2	V _{OUT2}	V _{DD3} output T _a = 25°C	-0.3 to V _{DD3} + 0.3	V
Output Voltage 3	V _{OUT3}	V _{DD} output, T _a = 25°C	-0.3 to V _{DD} + 0.3	V
Storage Temperature	T _{STG}	—	-55 to +150	°C

RECOMMENDED OPERATING CONDITIONS (3.0 V Spec.)(V_{SS} = 0 V)

Parameter	Symbol	Condition	Range	Unit
Operating Temperature	T _{op}	—	0 to +65	°C
Operating Voltage	V _{DD2}	—	2.7 to 3.5	V
	V _{DD}	—	V _{DD2} to 5.25	V
External 400kHz RC Oscillator Resistance	R _{OS}	—	90 to 500	kΩ
Crystal Oscillation Frequency	f _{XT}	—	30 to 66	kHz

ELECTRICAL CHARACTERISTICS (3.0 V Spec.)**DC Characteristics**(V_{SS} = 0 V, V_{DD2} = V_{DD} = 3.0 V, Ta = 0 to +65°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
V _{DD1} Voltage	V _{DD1}	C _a , C _b , C ₁₂ = 0.1 μF +100% -20%	1.3	1.5	1.7	V	1
V _{DD3} Voltage	V _{DD3}	C _a , C _b , C ₁₂ = 0.1 μF +100% -20%	4.3	4.5	4.7	V	
Crystal Oscillation Start Voltage	V _{STA}	Oscillation start time: within 5 seconds	2.7	—	—	V	
Crystal Oscillation Hold Voltage	V _{HOLD}	—	2.7	—	—	V	
Crystal Oscillation Stop Detection Time	T _{STOP}	—	0.1	—	1000	ms	
Internal Crystal Oscillator Capacitance	C _G	—	10	15	20	pF	
External Crystal Oscillator Capacitance	C _{GEX}	When external C _G used	10	—	30	pF	
Internal Crystal Oscillator Capacitance	C _D	—	10	15	20	pF	
Internal 400k RC Oscillator Capacitance	C _{OS}	—	8	12	16	pF	
400k RC Oscillation Frequency	f _{OSC}	External resistor R _{OS} = 100 kΩ V _{DD2} = 2.7 to 3.5 V	300	400	620	kHz	
POR Generation Voltage	V _{POR1}	When V _{DD2} is between V _{POR1} and 3.0 V	0	—	0.7	V	
POR Non-generation Voltage	V _{POR2}	No POR when V _{DD2} is between V _{POR2} and 3.0 V	2.7	—	3	V	

Notes: 1. "POR" denotes Power On Reset.

2. "T_{STOP}" indicates that if the crystal oscillator stops over the value of T_{STOP}, the system reset occurs.

DC Characteristics (continued)(V_{SS} = 0 V, V_{DD2} = V_{DD} = 3.0 V, Ta = 0 to +65°C unless otherwise specified)

Parameter	Symbol	Condition		Min.	Typ.	Max.	Unit	Measuring Circuit
Supply Current 1	I _{DD1}	CPU in halt state (400k RC oscillation halt)		—	1.0	4.0	μA	1
Supply Current 2	I _{DD2}	CPU in operating state (400k RC oscillation halt)		—	25	50	μA	
Supply Current 3	I _{DD3}	CPU in operating state (400k RC oscillation in operation)		—	220	450	μA	
Supply Current 4	I _{DD4}	Serial transfer, f _{SCK} = 300 kHz, CPU in operating state (400k RC oscillation halt)		—	30	60	μA	
Supply Current 5	I _{DD5}	CPU in halt state (400k RC oscillation halt), RC oscillator for A/D converter is in operating state	RT0 = 10 kΩ	—	300	450	μA	
			RT0 = 2 kΩ	—	1300	2000	μA	

1

DC Characteristics (continued)

($V_{SS} = 0$ V, $V_{DD1} = 1.5$ V, $V_{DD2} = V_{DD} = 3.0$ V, $V_{DD3} = 4.5$ V,
 $T_a = 0$ to $+65^\circ\text{C}$ unless otherwise specified)

Parameter (Pin Name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
Output Current 1 (P1.0)	I_{OH1}	$V_{OH1} = V_{DD} - 0.5$ V	-6.0	-2.0	-0.7	mA	2
	I_{OL1}	$V_{OL1} = 0.5$ V	3.0	8.0	25	mA	
	I_{OL1S}	$V_{DD} = 5$ V, $V_{OL1} = 0.5$ V	4.0	12	36	mA	
Output Current 2 (P1.1 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	I_{OH2}	$V_{OH2} = V_{DD} - 0.5$ V	-6.0	-2.0	-0.7	mA	2
	I_{OL2}	$V_{OL2} = 0.5$ V	0.7	2.0	6.0	mA	
	I_{OL2S}	$V_{DD} = 5$ V, $V_{OL2} = 0.5$ V	1.0	3.0	9.0	mA	
Output Current 3 (BD)	I_{OH3}	$V_{OH3} = V_{DD2} - 0.7$ V	-6.0	-2.0	-0.7	mA	2
	I_{OL3}	$V_{OL3} = 0.7$ V	0.7	2.0	6.0	mA	
Output Current 4 (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OH4}	$V_{OH4} = V_{DD2} - 0.1$ V	-2.5	-1.3	-0.7	mA	2
	I_{OL4}	$V_{OL4} = 0.1$ V	0.7	1.3	2.5	mA	
Output Current 5 (When L26 to L33 are configured as output ports)	I_{OH5}	$V_{OH5} = V_{DD} - 0.5$ V	-1.5	-0.6	-0.15	mA	2
	I_{OL5}	$V_{OL5} = 0.5$ V	0.15	0.6	1.5	mA	
	I_{OL5S}	$V_{DD} = 5$ V, $V_{OL5S} = 0.5$ V	0.2	0.7	2.0	mA	
Output Current 6 (OSC2)	I_{OH6}	$V_{OH6} = V_{DD2} - 0.5$ V	-6.0	-2.0	-0.7	mA	2
	I_{OL6}	$V_{OL6} = 0.5$ V	0.7	2.0	6.0	mA	
Output Current 7 (L0 to L33)	I_{OH7}	$V_{OH7} = V_{DD3} - 0.2$ V (V_{DD3} level)	—	—	-4.0	μA	2
	I_{OMH7}	$V_{OMH7} = V_{DD2} + 0.2$ V (V_{DD2} level)	4.0	—	—	μA	
	I_{OMH7S}	$V_{OMH7S} = V_{DD2} - 0.2$ V (V_{DD2} level)	—	—	-4.0	μA	
	I_{OML7}	$V_{OML7} = V_{DD1} + 0.2$ V (V_{DD1} level)	4.0	—	—	μA	
	I_{OML7S}	$V_{OML7S} = V_{DD1} - 0.2$ V (V_{DD1} level)	—	—	-4.0	μA	
	I_{OL7}	$V_{OL7} = 0.2$ V (V_{SS} level)	4.0	—	—	μA	
Output Leakage Current (P1.0 to P1.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3) (RT0, RT1, RS0, RS1, CRT0, CS0, CS1)	I_{OIH}	$V_{OH} = V_{DD2}$	—	—	0.3	μA	2
	I_{OIL}	$V_{OL} = V_{SS}$	-0.3	—	—	μA	

DC Characteristics (continued)

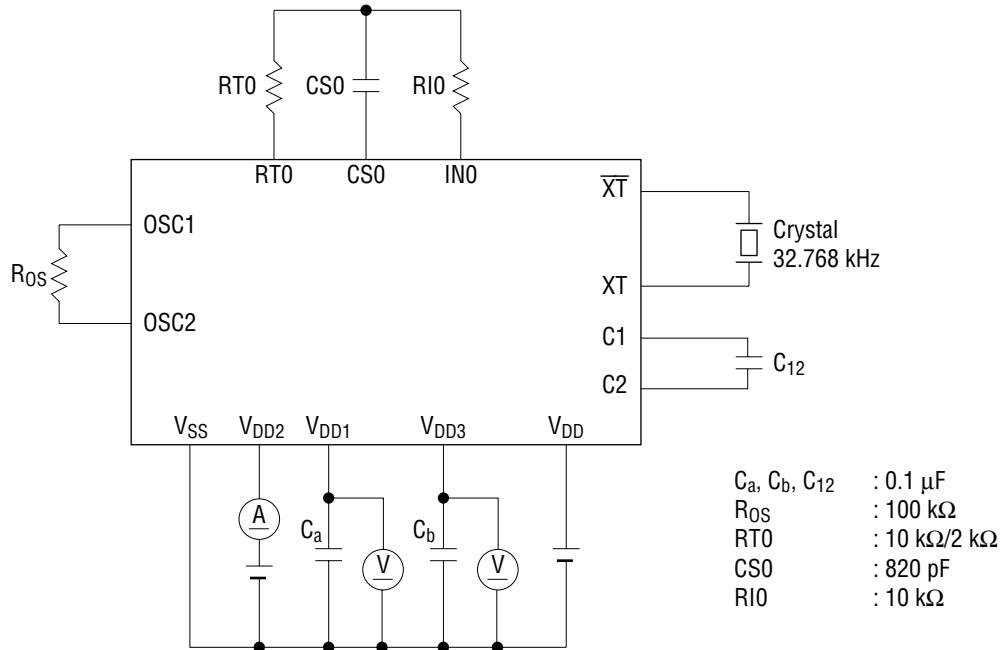
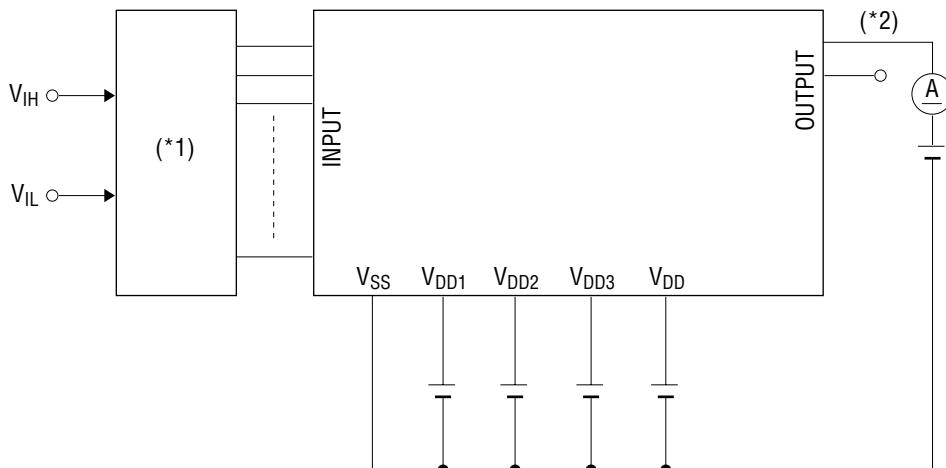
($V_{SS} = 0 \text{ V}$, $V_{DD1} = 1.5 \text{ V}$, $V_{DD2} = V_{DD} = 3.0 \text{ V}$, $V_{DD3} = 4.5 \text{ V}$,
 $T_a = 0 \text{ to } +65^\circ\text{C}$ unless otherwise specified)

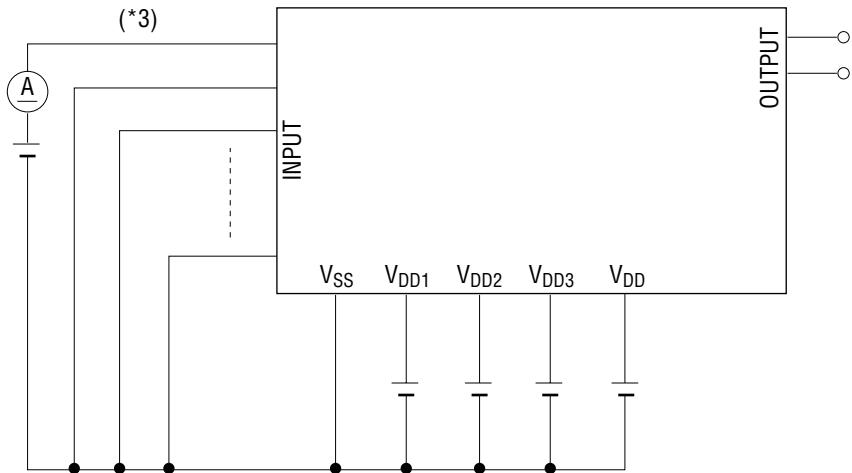
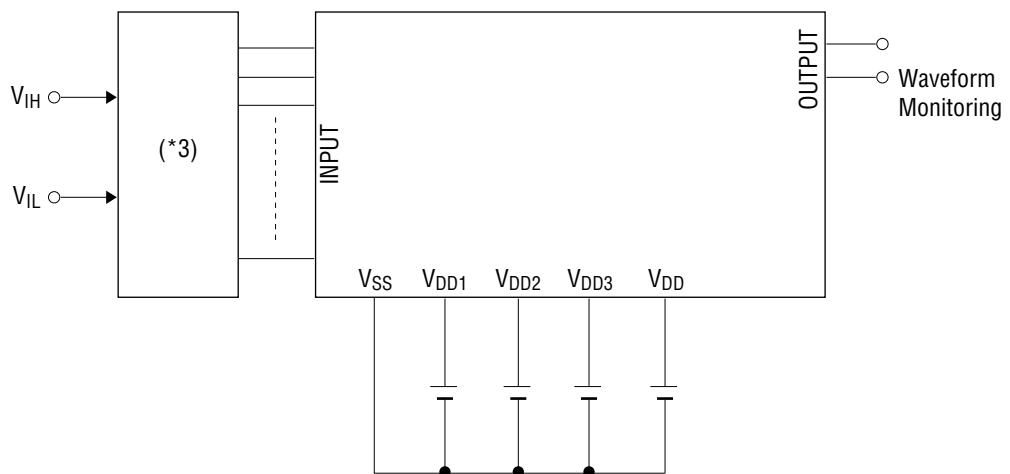
Parameter (Pin Name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
Input Current 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	I_{IH1}	$V_{IH1} = V_{DD}$ (when pulled down)	30	90	300	μA	3
	I_{IL1}	$V_{IL1} = V_{SS}$ (when pulled up)	-300	-90	-30	μA	
	I_{IH1S}	$V_{IH1} = V_{DD} = 5 \text{ V}$ (when pulled down)	80	250	800	μA	
	I_{IL1S}	$V_{IL1} = V_{SS}$, $V_{DD} = 5 \text{ V}$ (when pulled up)	-800	-250	-80	μA	
	I_{IH1Z}	$V_{IH1} = V_{DD}$ (in a high impedance state)	0	—	1.0	μA	
	I_{IL1Z}	$V_{IL1} = V_{SS}$ (in a high impedance state)	-1.0	—	0	μA	
Input Current 2 (IN0, IN1)	I_{IH2}	$V_{IH2} = V_{DD2}$ (when pulled down)	30	90	300	μA	3
	I_{IH2Z}	$V_{IH2} = V_{DD2}$ (in a high impedance state)	0	—	1.0	μA	
	I_{IL2Z}	$V_{IL2} = V_{SS2}$ (in a high impedance state)	-1.0	—	0	μA	
Input Current 3 (OSC1)	I_{IL3}	$V_{IL3} = V_{SS}$ (when pulled up)	-300	-110	-10	μA	4
	I_{IH3Z}	$V_{IH3} = V_{DD2}$ (in a high impedance state)	0	—	1.0	μA	
	I_{IL3Z}	$V_{IL3} = V_{SS}$ (in a high impedance state)	-1.0	—	0	μA	
Input Current 4 (RESET, TST1, TST2)	I_{IH4}	$V_{IH4} = V_{DD2}$	0	—	1.0	μA	4
	I_{IL4}	$V_{IL4} = V_{SS}$	-3.0	-1.5	-0.75	mA	
Input Voltage 1 (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	V_{IH1}	—	2.4	—	3.0	V	4
	V_{IL1}	—	0	—	0.6	V	
	V_{IH1S}	$V_{DD} = 5 \text{ V}$	4.0	—	5.0	V	
	V_{IL1S}	$V_{DD} = 5 \text{ V}$	0	—	1.0	V	
Input Voltage 2 (IN0, IN1, OSC1)	V_{IH2}	—	2.4	—	3.0	V	4
	V_{IL2}	—	0	—	0.6	V	
Input Voltage 3 (RESET, TST1, TST2)	V_{IH3}	—	2.4	—	3.0	V	4
	V_{IL3}	—	0	—	0.6	V	

DC Characteristics (continued)

($V_{SS} = 0$ V, $V_{DD1} = 1.5$ V, $V_{DD2} = V_{DD} = 3.0$ V, $V_{DD3} = 4.5$ V,
 $T_a = 0$ to $+65^\circ\text{C}$ unless otherwise specified)

Parameter (Pin Name)	Symbol	Condition	Min.	Typ.	Max.	Unit	Measuring Circuit
Hysteresis Width (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	ΔV_{T1}	—	0.2	0.5	1.0	V	4
	ΔV_{T1S}	$V_{DD} = 5$ V	0.25	1.0	1.5	V	
Hysteresis Width (RESET, TST1, TST2)	ΔV_{T2}	—	0.2	0.5	1.0	V	
Input Pin Capacitance (P0.0 to P0.3) (P2.0 to P2.3) (P3.0 to P3.3) (P4.0 to P4.3)	C_{IN}	—	—	—	5.0	pF	1

Measuring circuit 1**Measuring circuit 2**

Measuring circuit 3**Measuring circuit 4**

*1 Input logic circuit to determine the specified measuring conditions.

*2 Measured at the specified output pins.

*3 Measured at the specified input pins.

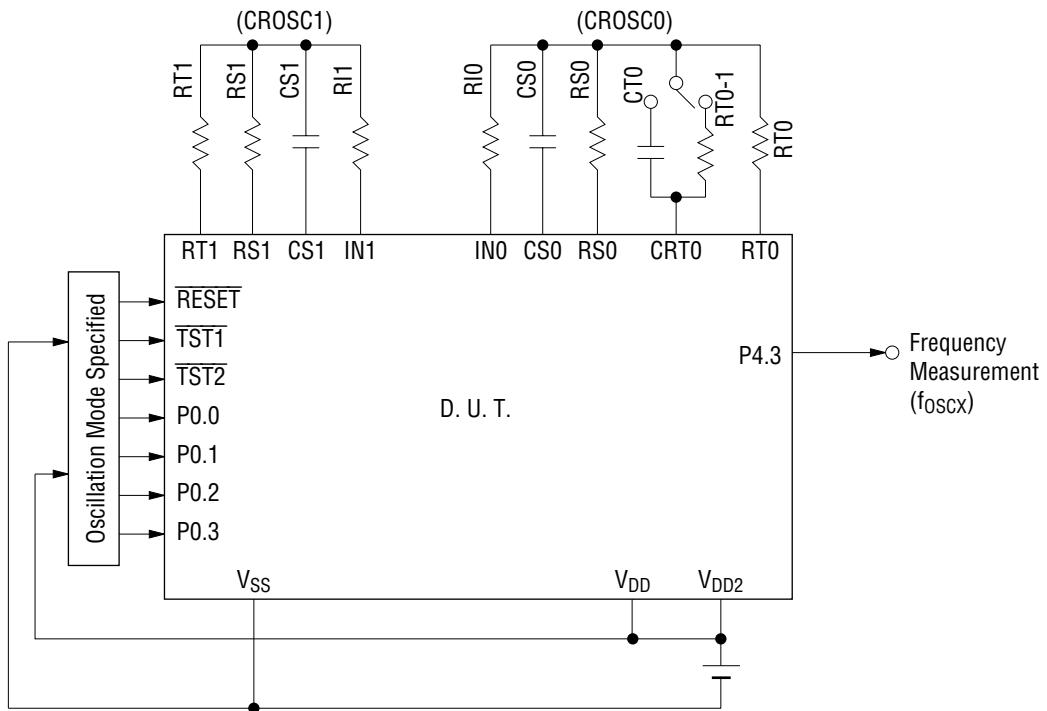
A/D Converter Characteristics(V_{SS} = 0 V, V_{DD2} = V_{DD} = 3.0 V, Ta = 0 to +65°C unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit	Measur-ing Circuit
Resistor for Oscillation	RS0, RS1, RT0, RT0-1, RT1	CS0, CT0, CS1 ≥ 740 pF	1.0	—	—	kΩ	5
Input Current Limiting Resistor	RI0, RI1	—	1.0	10	—	kΩ	
Oscillation Frequency	f _{OSC1}	Resistor for oscillation = 2 kΩ	200	239	277	kHz	
	f _{OSC2}	Resistor for oscillation = 10 kΩ	46.5	55.4	64.3	kHz	
	f _{OSC3}	Resistor for oscillation = 200 kΩ	2.79	3.32	3.85	kHz	
RS•RT Oscillation Frequency Ratio (*)	Kf1	RT0, RT0-1, RT1 = 2 kΩ	4.115	4.22	4.326	—	5
	Kf2	RT0, RT0-1, RT1 = 10 kΩ	0.990	1.0	1.010	—	
	Kf3	RT0, RT0-1, RT1 = 200 kΩ	0.0573	0.0616	0.0659	—	

* Kfx is the ratio of the oscillation frequency by a sensor resistor to the oscillation frequency by a reference resistor in the same condition.

$$Kfx = \frac{f_{oscx}(\text{RT0-CS0 Oscillation})}{f_{oscx}(\text{RS0-CS0 Oscillation})}, \frac{f_{oscx}(\text{RT0-1-CS0 Oscillation})}{f_{oscx}(\text{RS0-CS0 Oscillation})}, \frac{f_{oscx}(\text{RT1-CS1 Oscillation})}{f_{oscx}(\text{RS1-CS1 Oscillation})}$$

(x = 1, 2, 3)

Measuring circuit 5

RT0, RT0-1, RT1 = 2 kΩ/10 kΩ/200 kΩ

RS0, RS1 = 10 kΩ

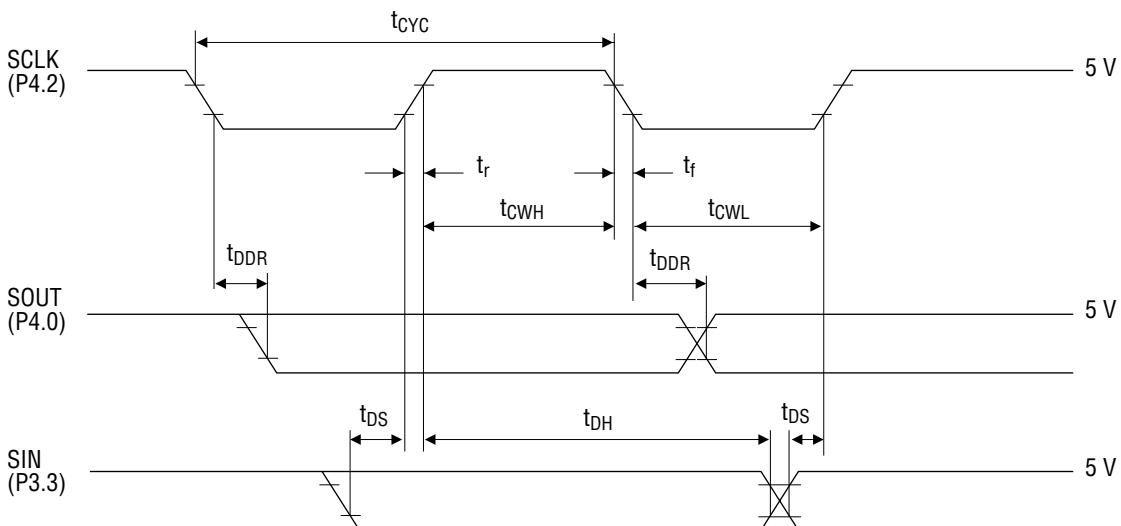
R10, RI1 = 10 kΩ

CS0, CT0, CS1 = 820 pF

AC Characteristics (Serial Interface)

(V_{SS} = 0 V, V_{DD2} = 3 V, V_{DD} = 5 V, Ta = 0 to +65°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
SCLK Input Fall Time	t _f	—	—	15	50	ns
SCLK Input Rise Time	t _r	—	—	15	50	ns
SCLK Input "L" Level Pulse Width	t _{CWL}	—	0.8	—	—	μs
SCLK Input "H" Level Pulse Width	t _{CWH}	—	0.8	—	—	μs
SCLK Input Cycle Time	t _{CYC}	—	2.0	—	—	μs
SCLK Output Cycle Time	t _{CYC1(0)}	CPU is operating at 32.768 kHz.	—	30.5	—	μs
SCLK Output Cycle Time	t _{CYC2(0)}	CPU is operating at 400 kHz.	—	2.5	—	μs
SOUT Output Delay Time	t _{DDR}	C _I = 10 pF	—	—	0.4	μs
SIN Input Setup Time	t _{DS}	—	0.5	—	—	μs
SIN Input Hold Time	t _{DH}	—	0.8	—	—	μs



("H" level = 4 V, "L" level = 1 V)

ABSOLUTE MAXIMUM RATINGS (1.5 V/3.0 V Spec., PROM Mode)(V_{SS} = 0 V)

Parameter	Symbol	Condition	Rating	Unit
PROM Power Supply Voltage	V _{CC}	V _{CC} = V _{DD1} = V _{DD2} , Ta = 25°C	-0.3 to +6.7	V
Program Voltage	V _{PP}	Ta = 25°C	-0.3 to +14.0	V
PROM Input Voltage	V _I	V _{CC} input, Ta = 25°C	-0.3 to V _{CC} + 0.3	V
PROM Output Voltage	V _O	V _{CC} output, Ta = 25°C	-0.3 to V _{CC} + 0.3	V
Storage Temperature	T _{STG}	—	-55 to +150	°C

RECOMMENDED OPERATING CONDITIONS (1.5 V/3.0 V Spec., PROM Mode)(V_{SS} = 0 V)

Parameter	Symbol	Condition	Range	Unit
Operating Temperature	T _{op}	—	0 to 65	°C
V _{CC} Power Supply Voltage	V _{CC}	V _{CC} = V _{DD1} = V _{DD2}	4.75 to 5.25	V
V _{PP} Power Supply Voltage	V _{PP}	During read	4.75 to 5.25	V
		During write	12.0 to 13.0	V
Input Voltage	V _{IH}	V _{CC} = V _{DD1} = V _{DD2}	4 to V _{CC}	V
	V _{IL}	—	0 to 1	V

ELECTRICAL CHARACTERISTICS (1.5 V/3.0 V Spec., PROM Mode)

(1) Read Operation

DC Characteristics $(V_{DD1} = V_{DD2} = V_{PP} = 5 \text{ V} \pm 5\%, Ta = 25^\circ\text{C} \pm 5^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
V _{CC} Power Supply Current (Standby)	I _{CC1}	$V_{CC} = V_{DD1} = V_{DD2}$ $\overline{CE} = V_{IH}$	—	—	35	mA
V _{CC} Power Supply Current (Operating)	I _{CC2}	$V_{CC} = V_{DD1} = V_{DD2}$ $\overline{CE} = V_{IL}$	—	—	100	mA
Input Voltage	V _{IH}	$V_{CC} = V_{DD1} = V_{DD2}$	4.0	—	V _{CC}	V
	V _{IL}	—	0	—	1.0	V
Output Current	I _{OH}	$V_{CC} = V_{DD1} = V_{DD2}$ $V_{OH} = V_{CC} - 0.5 \text{ V}$	-2.0	-0.7	-0.2	mA
	I _{OL}	$V_{OL} = 0.5 \text{ V}$	0.2	0.7	2.0	mA

AC Characteristics $(V_{CC} = 5 \text{ V} \pm 5\%, V_{PP} = V_{CC}, Ta = 25^\circ\text{C} \pm 5^\circ\text{C}$, unless otherwise specified)

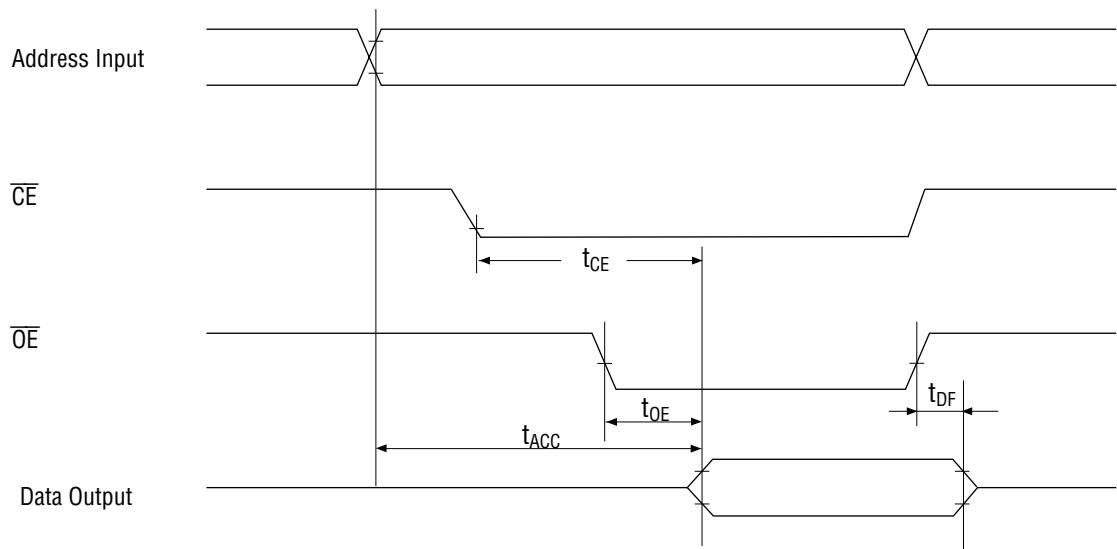
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Address Access Time	t _{ACC}	$\overline{OE} = \overline{CE} = V_{IL}$	—	—	120	ns
\overline{CE} Access Time	t _{CE}	$\overline{OE} = V_{IL}$	—	—	120	ns
\overline{OE} Access Time	t _{OE}	$\overline{CE} = V_{IL}$	—	—	50	ns
Output Disable Time	t _{DF}	$\overline{CE} = V_{IL}$	0	—	40	ns

Measurement conditions:

Input pulse level 0.45 V to 4.55 V

Input rise/fall time 5 ns

Threshold level input 0.8 V, 2 V / output 0.8 V, 2 V



(2) Write Operation

DC Characteristics $(V_{SS} = 0 \text{ V}, V_{DD1} = V_{DD2} = 5 \text{ V} \pm 5\%, V_{PP} = 12.5 \text{ V} \pm 0.5 \text{ V}, Ta = 25^\circ\text{C} \pm 5^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
V _{PP} Power Supply Current	I _{PP}	$\overline{CE} = V_{IL}$	—	—	50	mA
V _{CC} Power Supply Current	I _{CC}	$V_{CC} = V_{DD1} = V_{DD2}$	—	—	100	mA
Input Voltage	V _{IH}	$V_{CC} = V_{DD1} = V_{DD2}$	4.0	—	V _{CC}	V
	V _{IL}	—	0	—	1.0	V
Output Current	I _{OH}	$V_{CC} = V_{DD1} = V_{DD2}$ $V_{OH} = V_{CC} - 0.5 \text{ V}$	-2.0	-0.7	-0.2	mA
	I _{OL}	$V_{OL} = 0.5 \text{ V}$	0.2	0.7	2.0	mA

AC Characteristics $(V_{SS} = 0 \text{ V}, V_{DD1} = V_{DD2} = 5 \text{ V} \pm 5\%, V_{PP} = 12.5 \text{ V} \pm 0.5 \text{ V}, Ta = 25^\circ\text{C} \pm 5^\circ\text{C}$, unless otherwise specified)

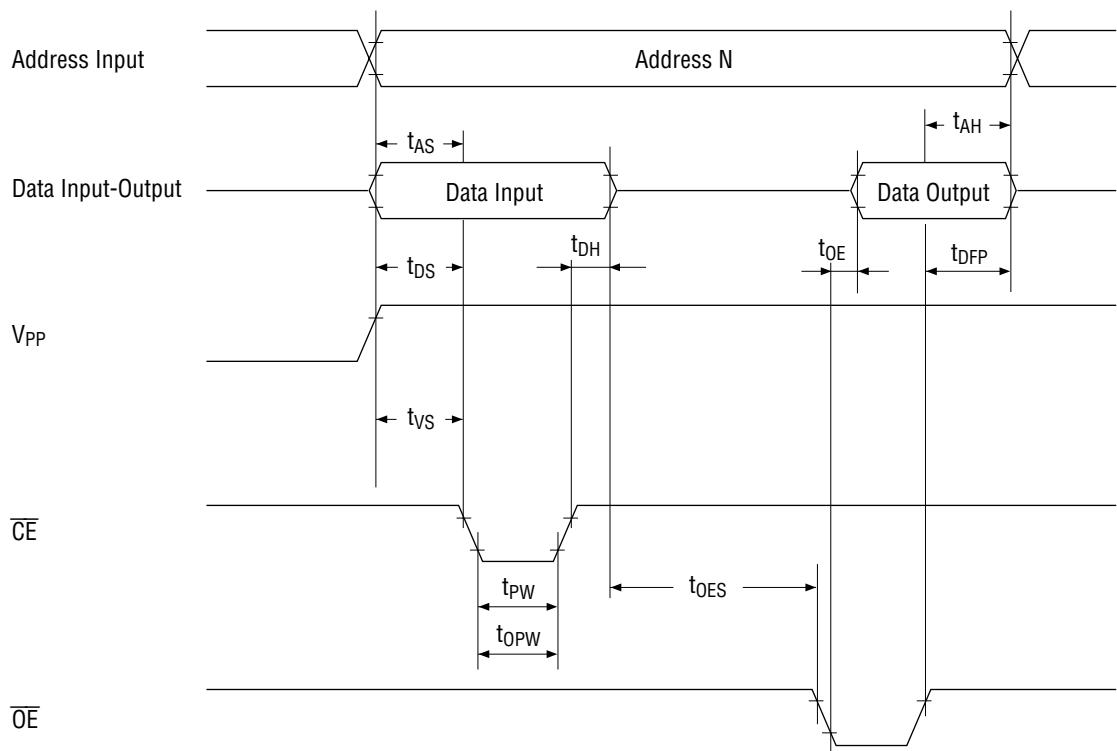
Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Address Setup Time	t _{AS}	—	2.0	—	—	μs
OE Setup Time	t _{OES}	—	2.0	—	—	μs
Data Setup Time	t _{DS}	—	2.0	—	—	μs
Address Hold Time	t _{AH}	—	0	—	—	μs
Data Hold Time	t _{DH}	—	2.0	—	—	μs
OE Output Floating Delay Time	t _{DFP}	—	0	—	130	ns
V _{PP} Power Source Setup Time	t _{VS}	—	2.0	—	—	μs
Initial Program Pulse Width	t _{PW}	$V_{DD1} = V_{DD2}$ 6 V ±0.25 V	0.95	1.0	1.05	ms
Additional Program Pulse Width	t _{OPW}	$V_{DD1} = V_{DD2}$ 6 V ±0.25 V	2.85	—	78.75	ms
OE Output Effective Delay Time	t _{OE}	—	—	—	150	ns

Measurement conditions:

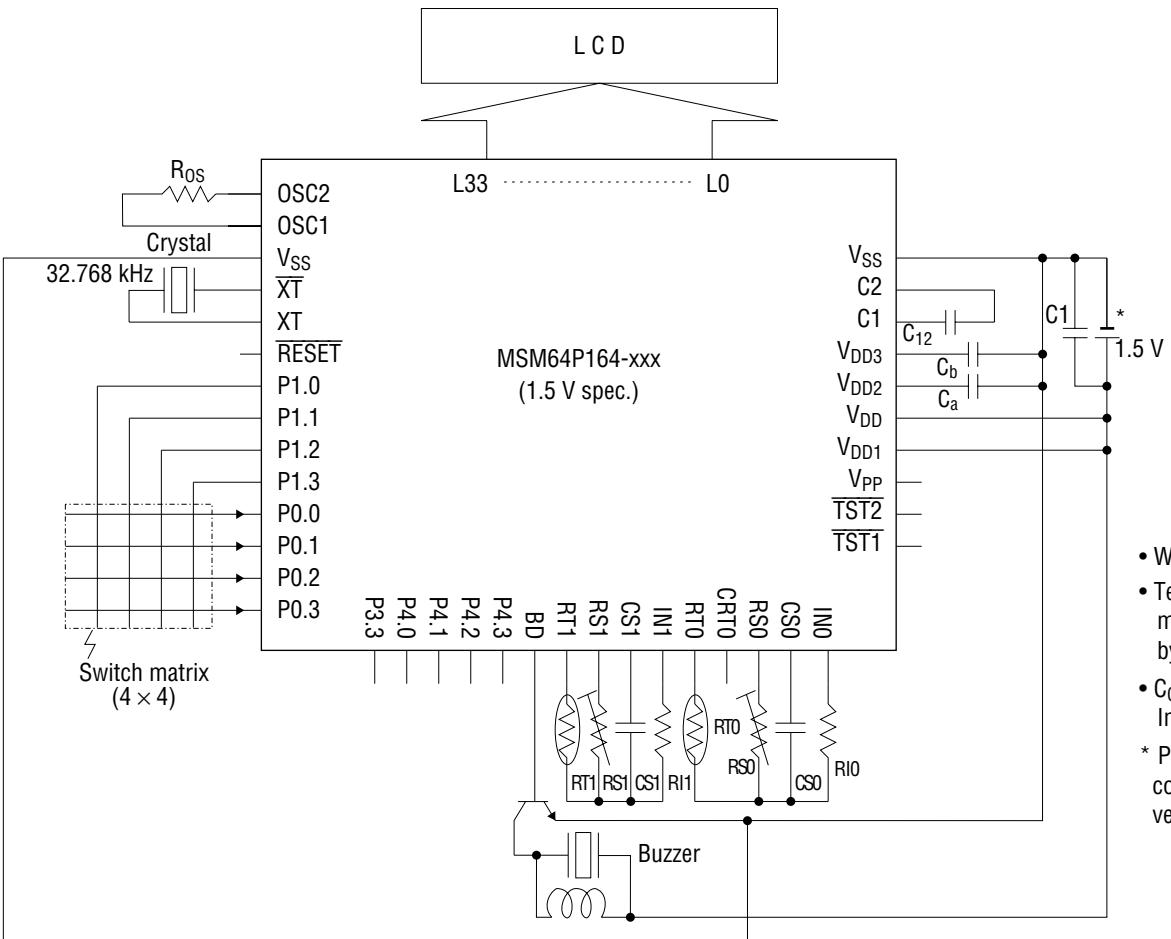
Input pulse level 0.45 V to 4.55 V

Input rise/fall time less than 20 ns

Threshold level input 0.8 V, 2 V/output 0.8 V, 2 V

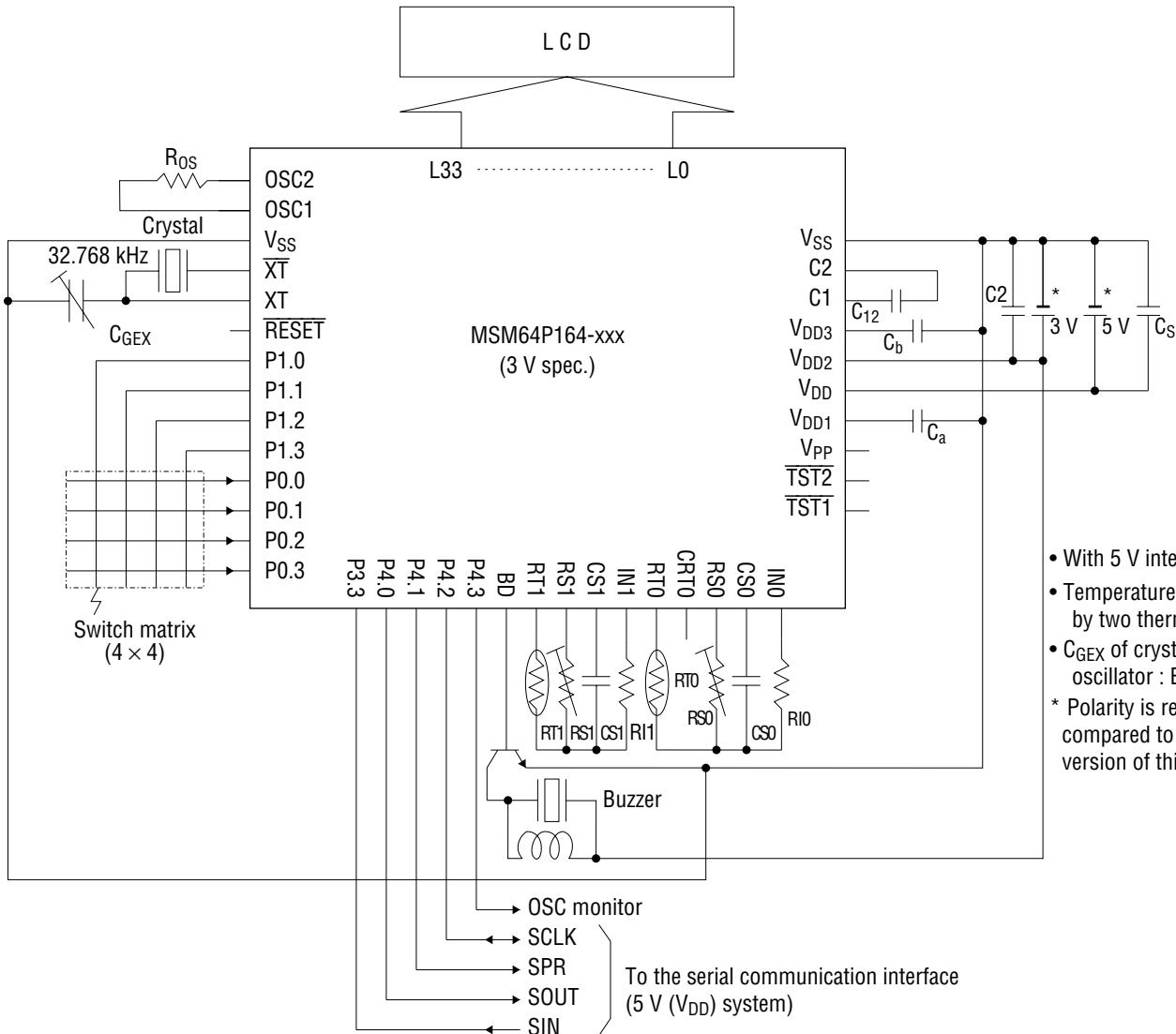


APPLICATION CIRCUITS



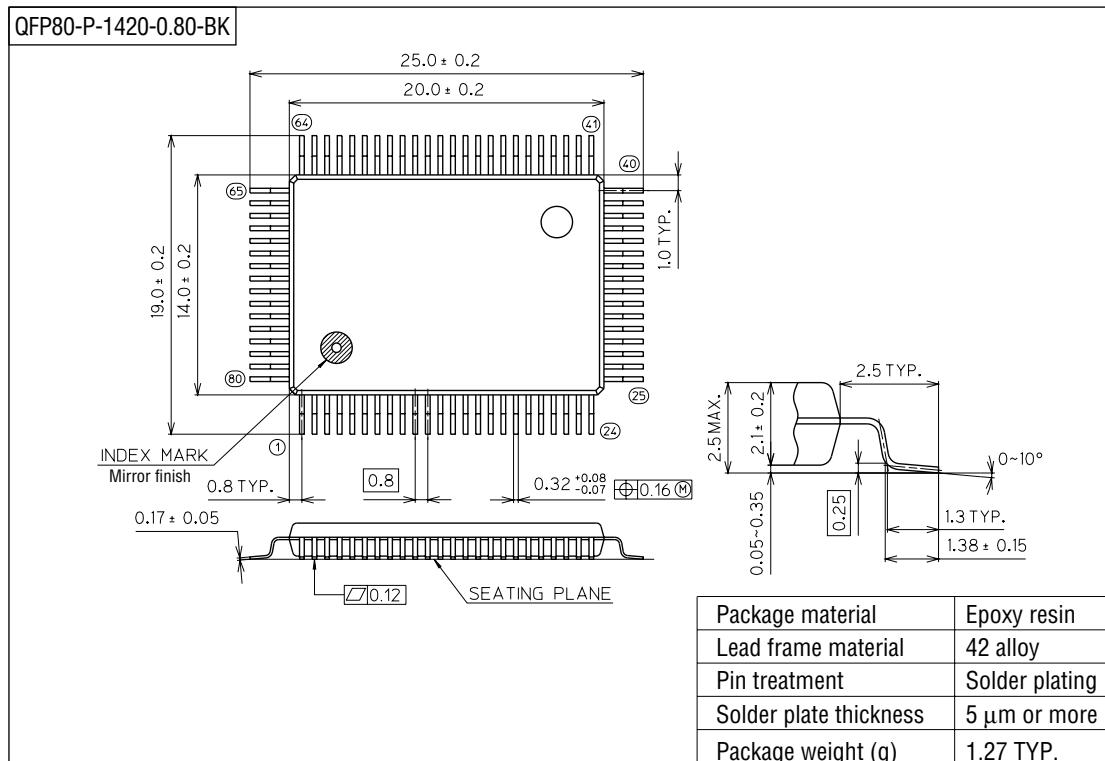
- Without 5 V interface
 - Temperature measurement by two thermistors
 - C_G of crystal oscillator : Internal
- * Polarity is reversed when compared to mask ROM version of this device.

APPLICATION CIRCUITS (continued)



PACKAGE DIMENSIONS

(Unit : mm)



Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, TQFP, LQFP, SOJ, QFJ (PLCC), SHP, and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage. Therefore, before you perform reflow mounting, contact Oki's responsible sales person on the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

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2. The outline of action and examples for application circuits described herein have been chosen as an explanation for the standard action and performance of the product. When planning to use the product, please ensure that the external conditions are reflected in the actual circuit, assembly, and program designs.
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